

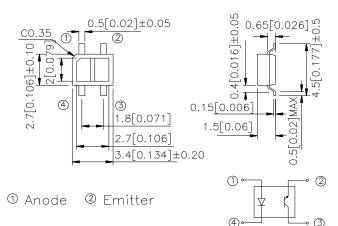
SUBMINIATURE, HIGH SENSITIVITY PHOTOINTERRUPTER

*Features

- Compact and thin.
- Visible light cut-off type.
- High sensitivity.
- Package:1000pcs/Reel.
- Moisture sensitivity level : level 4.
- RoHS Compliant.

*Applications

- Cassette tape recorders, VCRs.
- Floppy disk drives.
- Various microcomputerized control equipment.



3 Collector
Cathode

UNIT : MM[INCH]

TOLERANCE: $\pm 0.25[\pm 0.01]$ UNLESS OTHERWISE NOTED.

*Absolute Maximum Ratings

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	50	mA
	Reverse voltage	V_R	6	V
	Power dissipation	P _D	75	mW
	Peak Forward Current (Pulse Width ≤100uS, Duty Cycle =1%)	I _{FP}	1	А
Output	Collector-emitter voltage	V _{CEO}	35	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	Ic	20	mA
	Collector power dissipation	Pc	75	mW
Operating temperature		Topr	-25~+85	°C
Storage temperature		Tstg	-40~+100	°C
soldering temperature (1/16 inch from body for 5 seconds)		Tsol	260	°C





SPEC NO: DSAB2475 REV NO: V.12 DATE: JAN/21/2010 PAGE: 1 OF 6
APPROVED: WYNEC CHECKED: Tracy Deng DRAWN: Z.Q.NI ERP:1206000001

■Electro-optical Characteristics

	Parameter		Symbol	Conditions	Min.	TYP.	Max.	Unit
Input	Forward Voltage		V_{F}	I _F =20mA	1.0	1.2	1.5	V
	Reverse Current		I _R	V _R =6V	-	-	10	μΑ
	Peak Wavelength		λР	I _F =20mA	-	940	-	nm
Output	Collector Dark C	urrent	I _{CEO}	V _{CE} =20V	-	10 ⁻⁹	10 ⁻⁷	Α
	*1 Collector Current		Ic	V _{CE} =2V I _F =4mA	10	-	400	μА
Transfer charact-	*2 Leak Current		I _{LEAK}	V _{CE} =2V I _F =4mA	-	-	0.1	μА
eristics	Response time	Rise time	tr	V _{CE} =2V	-	20	100	μsec
		Fall time	tf	$I_C=100\mu A$ $R_L=1K\Omega,d=1mm$	-	20	100	μsec

^{*1} The condition and arrangement of the reflective object are shown below.

■ Classification table of radiant flux

BIN CODE	E	F	G
Ic (μA)	10~120	100~250	200~400

Test Condition and All evaporation Arrangement for Collector Current

Fig. 1 Forward Current vs.
Forward Voltage

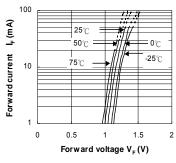


Fig. 3 Collector Current vs.
Collector-emitter Voltage

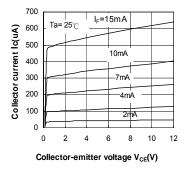


Fig. 2 Collector Current vs. Forward Current

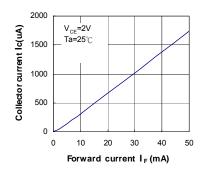
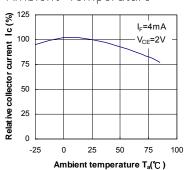


Fig. 4 Relative Collector Current vs. Ambient Temperature

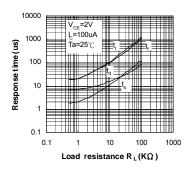


SPEC NO: DSAB2475 REV NO: V.12 DATE: JAN/21/2010 PAGE: 2 OF 6
APPROVED: WYNEC CHECKED: Tracy Deng DRAWN: Z.Q.NI ERP:1206000001

^{*2} Without reflective object.

Fig. 5 Response Time vs. Load Resistance

Test Circuit for Response Time



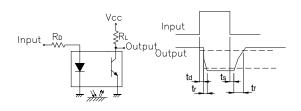
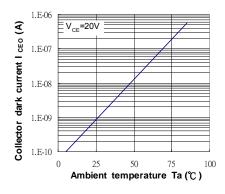


Fig. 6 Collector Dark Current vs. Fig. 7 Relative Collector Current vs.

Ambient Temperature Distance between Sensor and
Al Evaporation Glass



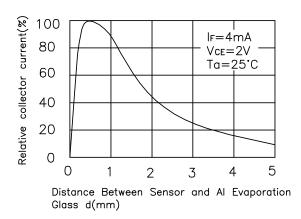
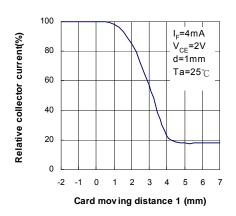
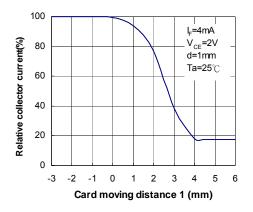


Fig. 8 Relative Collector Current vs. Fig. 9 Relative Collector Current vs. Card Moving Distance (1) Card Moving Distance (2)





SPEC NO: DSAB2475 REV NO: V.12 DATE: JAN/21/2010 PAGE: 3 OF 6
APPROVED: WYNEC CHECKED: Tracy Deng DRAWN: Z.Q.NI ERP:1206000001



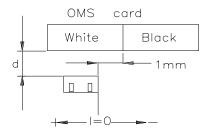
Test Condition for Distance & Detecting PositionCharacteristics

Correpond to Fig. 7



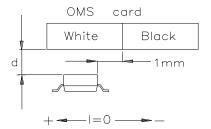
Correpond to Fig. 8
Test condition

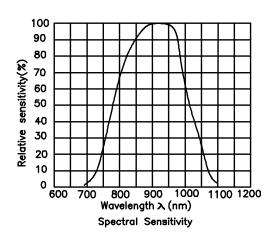
 $I_F=4mA$ $V_{CE}=2V$ d=1mm



Correpond to Fig. 9
Test condition

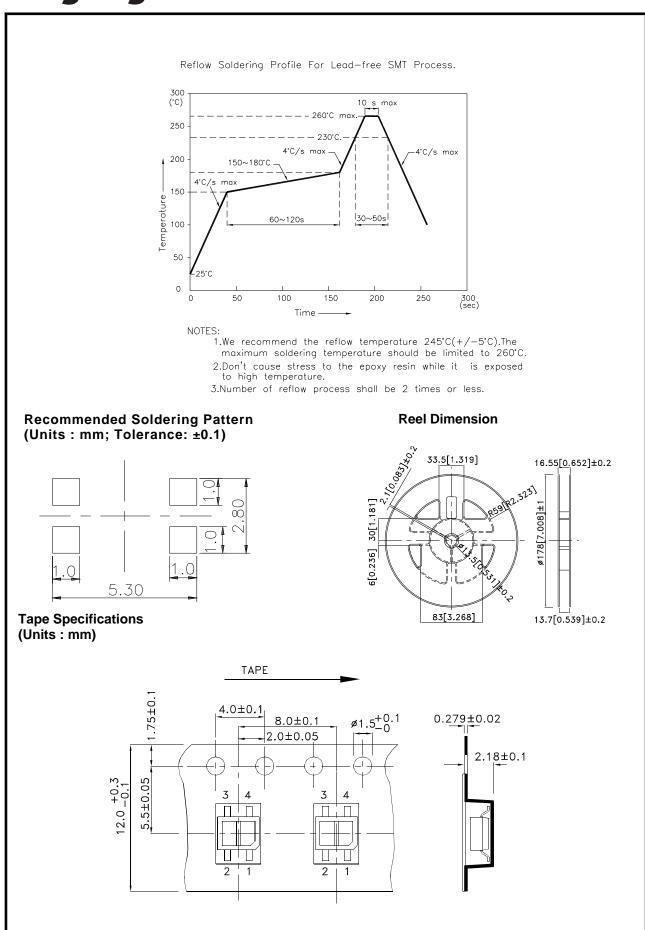
 $I_F=4mA$ $V_{CE}=2V$ d=1mm





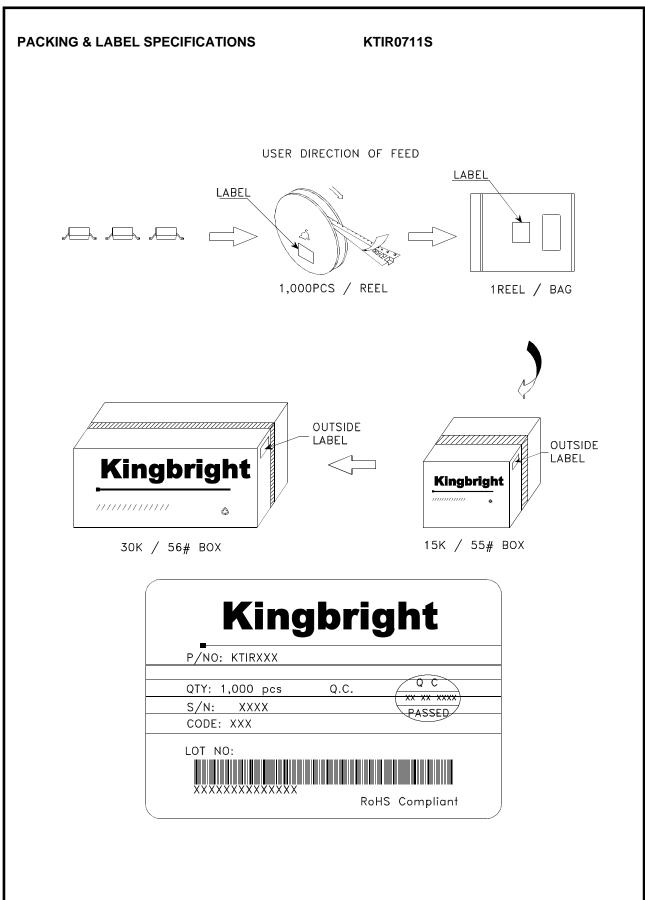
SPEC NO: DSAB2475 APPROVED: WYNEC REV NO: V.12 CHECKED: Tracy Deng DATE: JAN/21/2010 DRAWN: Z.Q.NI PAGE: 4 OF 6 ERP:1206000001





SPEC NO: DSAB2475 REV NO: V.12 DATE: JAN/21/2010 PAGE: 5 OF 6
APPROVED: WYNEC CHECKED: Tracy Deng DRAWN: Z.Q.NI ERP:1206000001





SPEC NO: DSAB2475 APPROVED: WYNEC REV NO: V.12 CHECKED: Tracy Deng DATE: JAN/21/2010 DRAWN: Z.Q.NI PAGE: 6 OF 6 ERP:1206000001